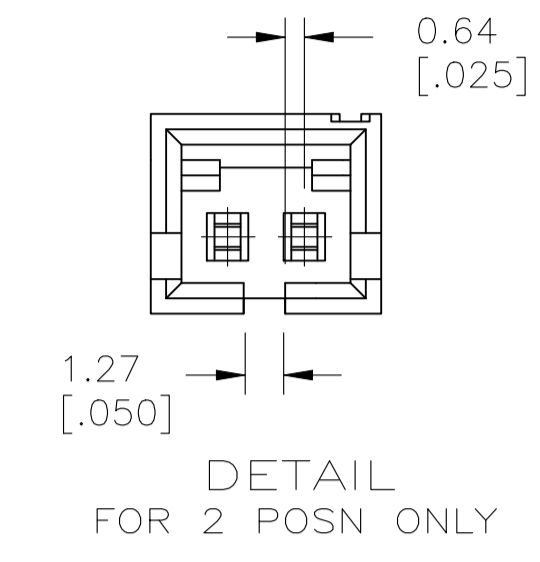
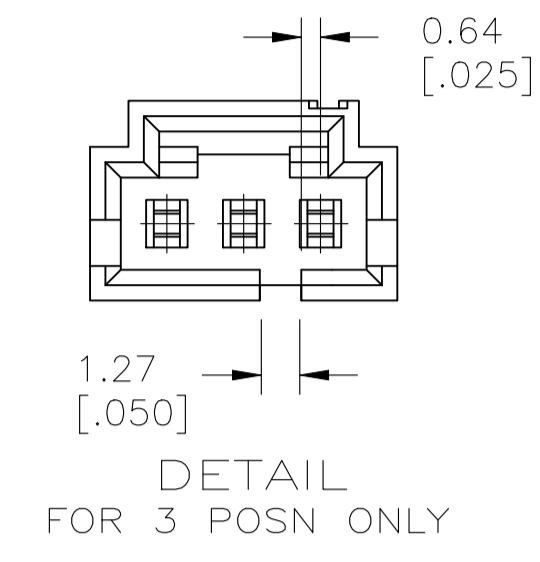
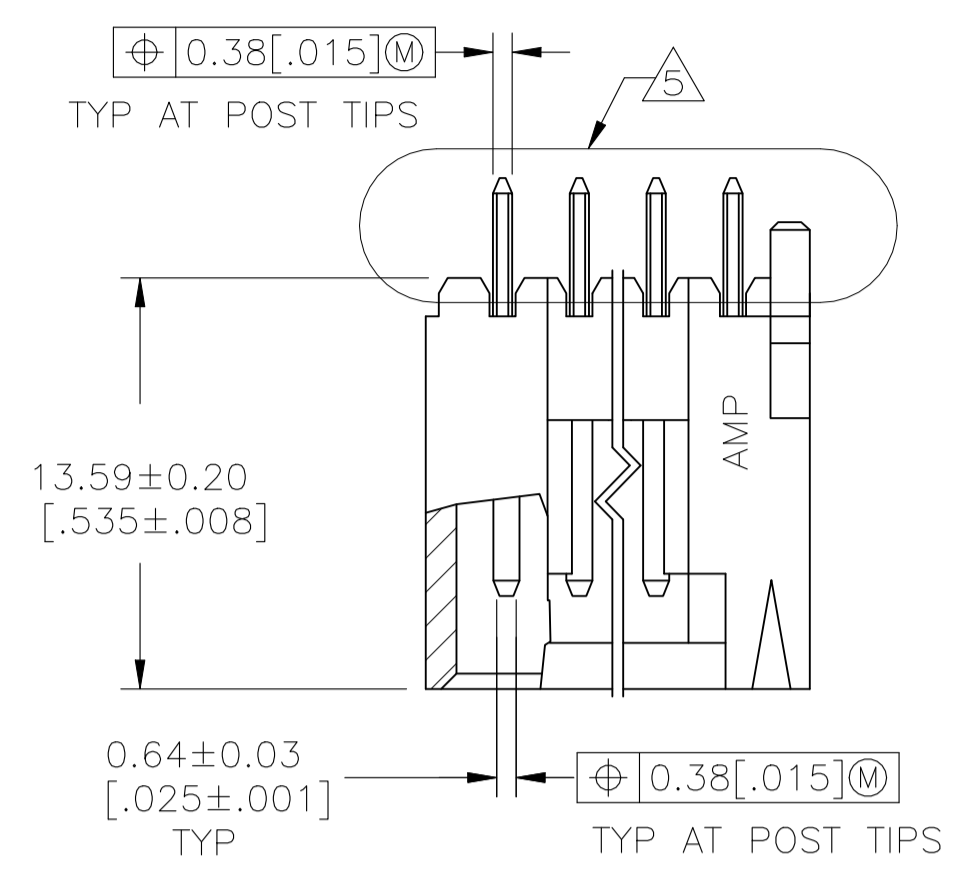
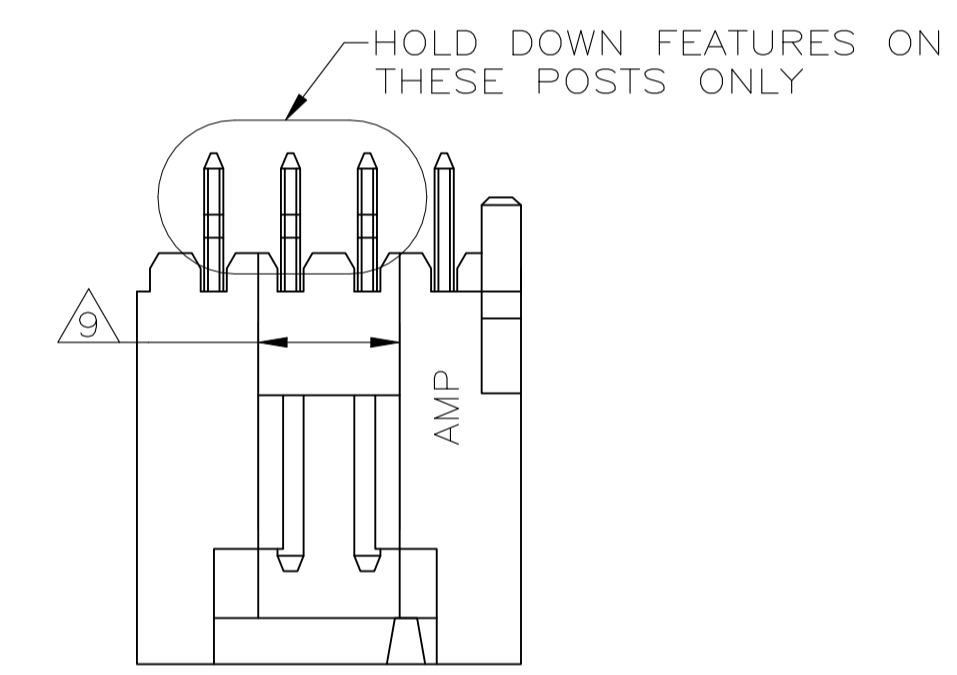
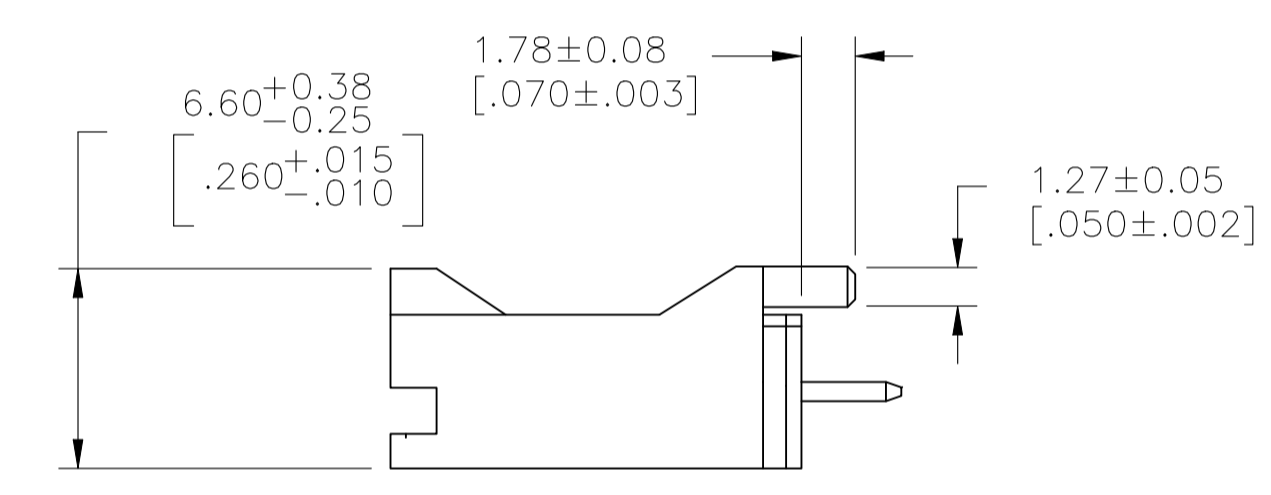
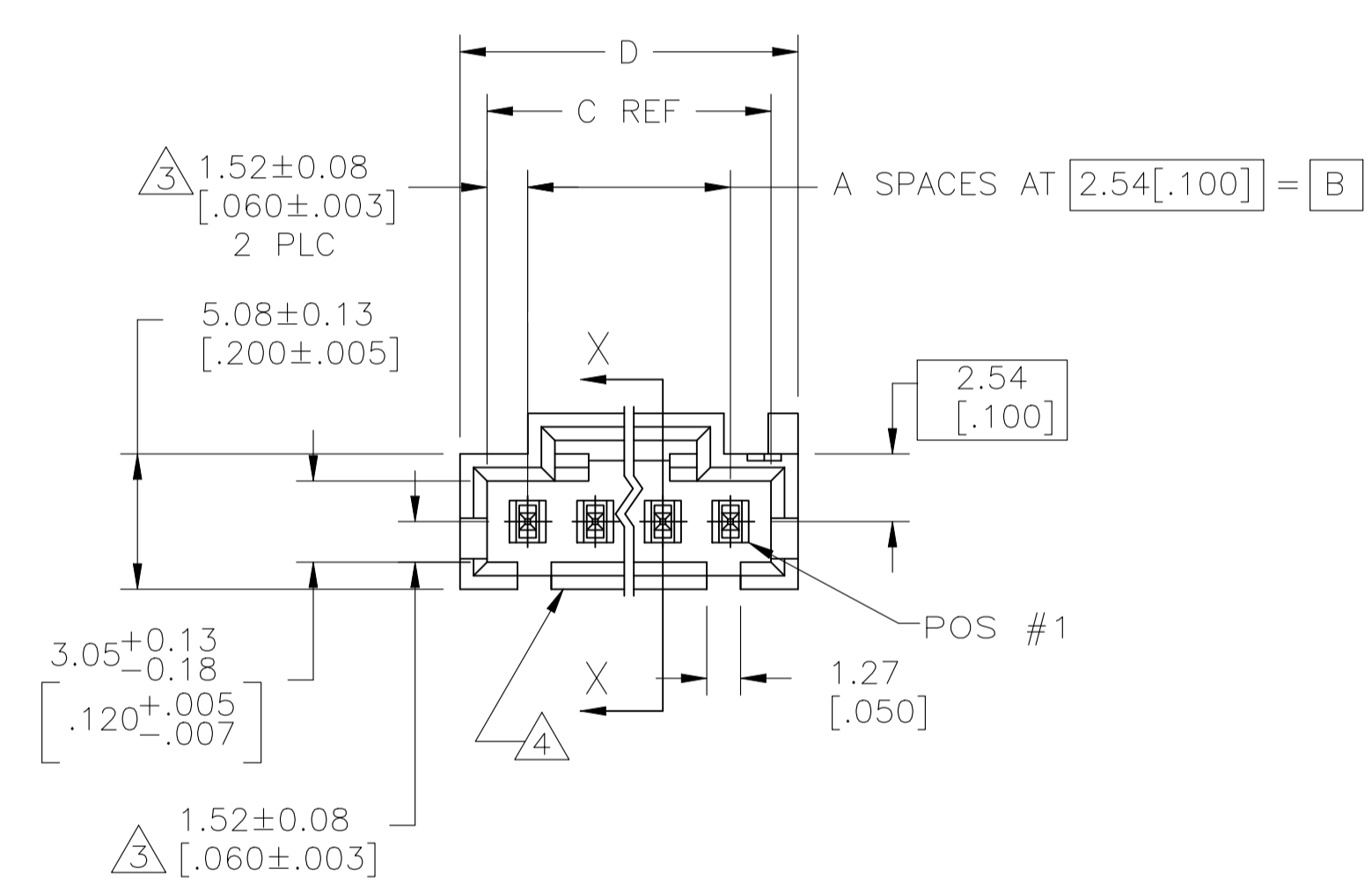


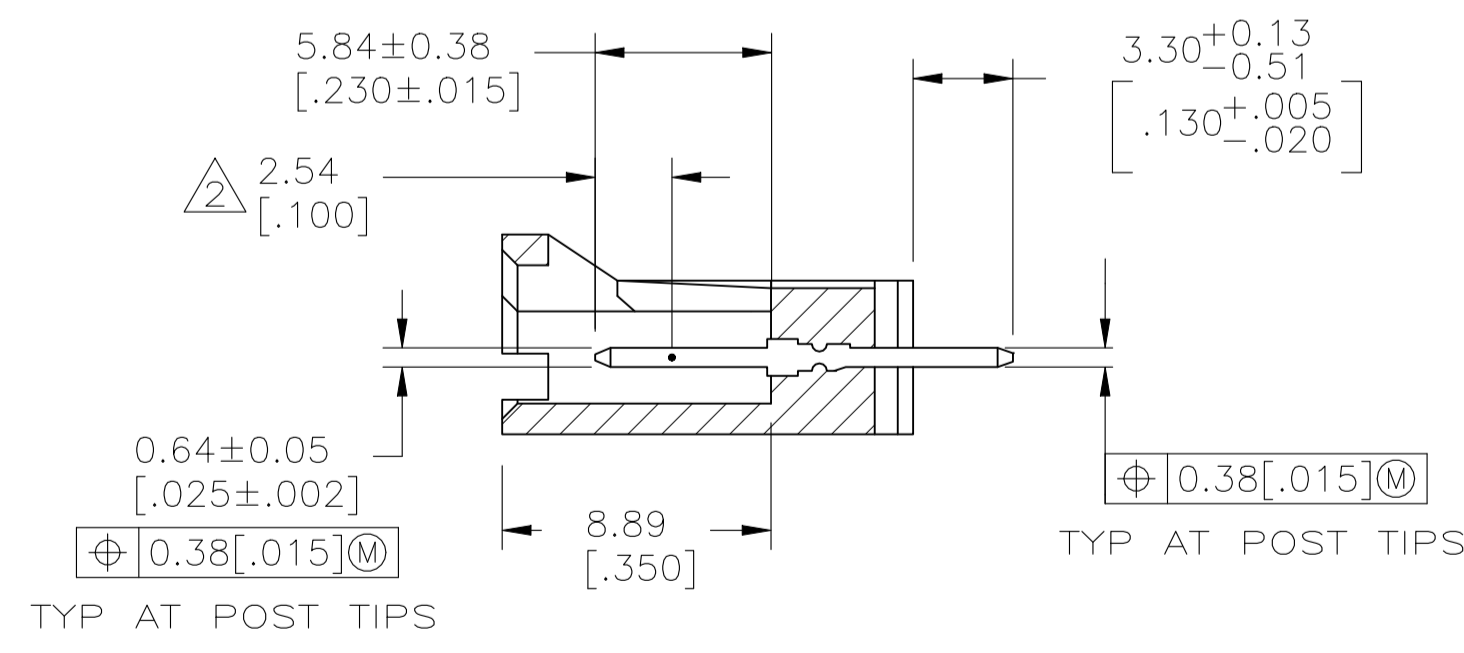
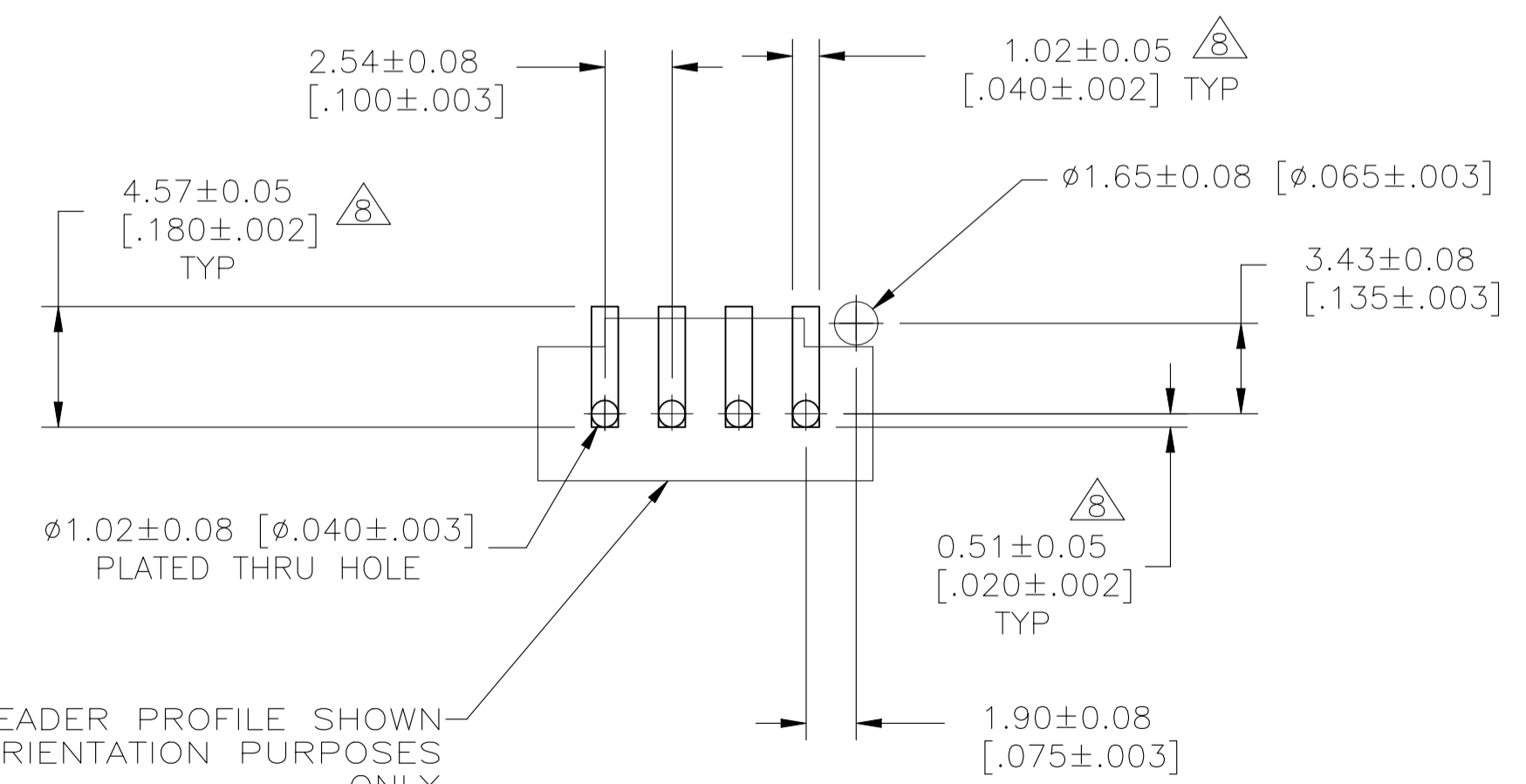
REVISIONS					
REV	DESCRIPTION	DATE	BY	APP'D	
A	REVISED PER ECO-20-001912	03JUN2020	SB	JO	



- ① 0.00254-0.00508 [.000100-.000200] TIN OVER
0.00127 [.000050] NICKEL.
- ② POINT OF MEASUREMENT FOR PLATING THICKNESS
- ③ THESE DIMENSIONS APPLY WHERE THE POST INTERSECTS THE HOUSING
- ④ ON ASSEMBLIES WITH FOUR OR MORE POSITIONS, TWO POLARIZATION SLOTS.
- ⑤ SELECT POST TAILS FORMED TO PROVIDE CONNECTOR HOLD DOWN UNTIL SOLDERED (SEE DETAIL Z).
- ⑥ MATERIAL: HOUSING- HIGH TEMP THERMOPLASTIC, COLOR-SEE TABLE.
POSTS- BRASS.
- ⑦ PRELIMINARY PART - NOT RELEASED FOR PRODUCTION.
- ⑧ DIMENSIONS NOTED ARE FOR SOLDER STENCIL LAYOUT USE WITH 1.58 ± 0.20 [.062 ± .008] THICK PRINTED CIRCUIT BOARDS.
- ⑨ 0.25 [.010] RECESS PERMISSIBLE IN THIS AREA FOR MOLD SHUT OFF



HOLD DOWN CONFIGURATION FOR 4 POSITION ASSEMBLY ONLY

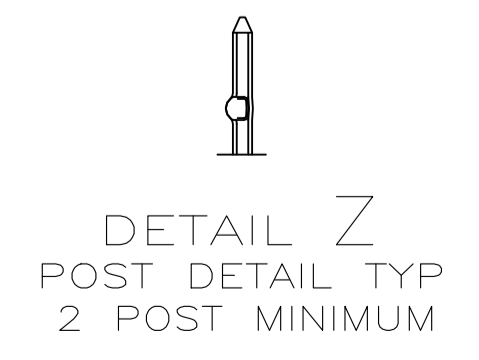


SECTION X-X

REV	D	C	B	A	NO OF POSN	ASSEMBLY PART NUMBER
①	15.24 [.600]	13.21 [.520]	10.16 [.400]	4	5	1571194-4
②	12.7 [.500]	10.67 [.420]	7.62 [.300]	3	4	1571194-3
③	10.16 [.400]	8.13 [.320]	5.08 [.200]	2	3	1571194-2
④	7.62 [.300]	5.59 [.220]	2.54 [.100]	1	2	1571194-1

HEADER PROFILE SHOWN FOR ORIENTATION PURPOSES ONLY

RECOMMENDED PC BOARD MOUNTING DIMENSIONS
RECOMMENDED STENCIL THICKNESS = 0.25 [.010]



THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN R BROWN 02JAN02		TE Connectivity	
DIMENSIONS: mm [INCHES]		TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD J GESFORD 02JAN02	
0 PLC ± -		1 PLC ± -		NAME: HEADER ASSY, AMPMODU MTE, VERTICAL, WITH LATCH, SINGLE ROW, .100 CL, .025 SQ POSTS, PCB ORIENTATION, RETENTIVE POSTS, SPECIAL PLATING	
2 PLC ± -		3 PLC ± 0.38 [.005]		PRODUCT SPEC: 108-25034	
4 PLC ANGLES ± -		FINISH: SEE NOTE 1		APPLICATION SPEC: -	
MATERIAL: SEE NOTE 6		WEIGHT: -		SIZE: CAGE CODE: DRAWING NO: A1 00779 C=1571194	
CUSTOMER DRAWING		SCALE: 4:1		SHEET 1 OF 1 REV A	